



PRINTED CIRCUIT BOARDS
INTERCONNECTION CARRIERS

State of the Art: PCB's

Revisio

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01

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 105 FR4 35 L71.35 P10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_105_FR4_35_L71.35_p10

Layers	in μ	Material	Build-Up	Assembly
Layer-1	35 μ	Copper	 (100 μ PrePreg-Type: 2125)	} A1 } B
	100 μ	Prepreg		
Layer-2	35 μ	Copper		
	710 μ	L-FR4		
Layer-3	35 μ	Copper		
	100 μ	Prepreg		
Layer-99	35 μ	Copper		

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